

Abstract

A method and apparatus for adding slurry using a moveable outlet, such as one or more moveable arms, in a semiconductor wafer polishing system. The end of the slurry arm could be set to fan out the slurry as the slurry is dispensed onto the pad. Preferably, the arm is set so that the distance and centering of the arm is controlled by the setup of the process. The arm could be set to move in an arc, or to move in and out on a set track. Regardless, the slurry is preferably sprayed onto the pad in the location needed to place the slurry on the pad, but only in the areas that are needed. This increases the control of the uniformity of the process, and preferably reduces the total amount of slurry that is used in the process.